

Molded Interconnect Device (MID) Market based on by Product Type (Antennae & Connectivity, Sensor),by Process (Laser Direct Structuring, Two-shot Molding), by Industry (Consumer Electronics, Telecommunication, Medical) and Geography– Global Forecast up to 2030

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Abstracts

In order to estimate the present size of the moulded interconnect device (MID) market, the study covered four main tasks. To gather data about the market, as well as its parent and peer markets, in-depth secondary research was conducted. The following stage involved conducting primary research to confirm these conclusions, hypotheses, and sizing with industry experts throughout the value chain. Two methodologies were utilised to approximate the overall market size: top-down and bottom-up. The size of the market for each section and subsegment was then estimated using data triangulation and market breakdown.

Numerous primary sources from the supply and demand sides were questioned during the main research phase to gather crucial qualitative and quantitative data for this report. Industry specialists including CEOs, VPs, marketing directors, directors of technology and innovation, and associated executives from significant firms and organisations in the moulded interconnect device (MID) sector were the main sources from the supply side. Following the completion of market engineering, which involved the computation of market statistics, market breakdown, market size estimates, market forecasting, and data triangulation, a significant amount of primary research was carried out in order to collect data and confirm and validate the crucial figures that were determined.

Several data triangulation techniques, in addition to top-down and bottom-up approaches, have been used throughout the market engineering process to estimate and validate the size of the dependent submarkets described in this study, as well as the moulded interconnect device (MID) market.

Molded Interconnect Device (MID) Market based on Product Type:

Antennae & Connectivity Modules

Sensors

Connectors & Switches

Lighting Systems

Others

Molded Interconnect Device (MID) Market based on Process:

Laser Direct Structuring (LDS)

Two-Shot Molding

Film Techniques

Molded Interconnect Device (MID) Market, by Vertical:

Telecommunications

Consumer Electronics

Automotive

Medical

Industrial

Military & Aerospace

Molded Interconnect Device (MID) Market based on Geography:

North America

US

Canada

Europe

Germany

UK

France

Italy

Spain

Rest of Europe (RoE)

Asia Pacific (APAC)

China

Japan

India

Australia

South Korea

Rest of Asia Pacific (RoAPAC)

Latin America (LATAM)

Brazil

Argentina

Rest of South America

Middle East and Africa (MEA)

UAE

Turkey

Saudi Arabia

South Africa

Rest of Middle East & Africa

The market for moulded connecting devices is divided into product categories such as lighting systems, sensors, connectors & switches, antennas & connectivity modules, and others. The category that generated the largest revenue share in the moulded interconnect device market in 2021 was antennas & connectivity modules. MIDs allow for the creation of new functionality as well as the downsizing of products because they can integrate mechanical and electrical components into nearly any type of connecting device.

The moulded interconnect device market is divided into three segments based on process: film methods, two-shot moulding, and laser direct structuring (LDS). In 2021, the moulded interconnect device market had a sizable revenue share from the two-shot moulding segment. A reliable and well-established technique for creating MIDs that is both affordable and consistent is two-shot moulding. The part is being made in two-shot moulding using two distinct moulding cycles, various thermostatic polymers, and an electroless plating procedure.

The market for moulded interconnect devices is divided into the following vertical segments: consumer electronics, automotive, medical, industrial, military & aerospace,

and telecommunications. With the largest revenue share in the moulded interconnect device market in 2021, the consumer electronics category held the top spot. Electronic gadgets intended for daily use, such as those for entertainment, communications, and workplace productivity, are known as consumer electronics. Consumer electronics include almost all electronic equipment used for work, play, and communication.

The cloud native storage market is examined in North America, Europe, Asia Pacific, and Latin America based on region. The market for moulded interconnect devices saw its highest revenue share in the Asia Pacific region in 2021. The main causes of this include a number of Asian OEMs as well as producers of semiconductor devices and goods. In especially in South Korea, Taiwan, and China, the area has excelled in offering the most cutting-edge semiconductor fabrication services as well as electronic system assembly services. In addition, semiconductor electronics manufacturers gain a great deal from outsourcing their production to places like Taiwan and China.

This report illustrates the most vital attributes of the Molded Interconnect Device (MID) Market, which are driving and providing opportunities.

This research gives an in-depth analysis of the Molded Interconnect Device (MID) Market growth on the basis of several segments in the market.

This report presents the predictions of the past and present trends of the Molded Interconnect Device (MID) Market.

This study also presents the competitive analysis, such as key strategies and capabilities of major players of the Molded Interconnect Device (MID) Market.

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